

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF THE CLAIMS

Claims 1-29 (canceled)

30. (currently amended) A fan out type package structure, comprising:
a base ~~without a die receptor cavity formed therein;~~
an adhesion material formed on said base;
a die having a plurality of pads on a top surface that is opposite a bottom surface which is
~~adhered on said base-adhesion material;~~
a first dielectric layer formed on said base and filled in a space except said die on said base;
a second dielectric layer formed on said first dielectric layer and said die, wherein said second dielectric layer including a plurality of openings for contact with said plurality of pads;
a contact conductive layer formed on said plurality of pads of said die and within said openings to electrically ~~coupling-couple~~ with said pads, respectively;
a plurality of conductive lines formed on said second dielectric layer and in contact with, said contact conductive layer and substantially ~~refilling in~~ filling said openings, and said conductive lines being extended out from corresponding said contact conductive layer to corresponding end points, ~~wherein said corresponding end points are inside a surface of said second dielectric layer,~~
an isolation layer formed on said conductive lines and said second dielectric layer; and
solder balls passing through said isolation layer welded on said conductive lines for coupling with said conductive lines, respectively.
31. (currently amended) The package structure in claim 30, wherein surfaces of said first dielectric layer and said ~~first~~ die are at the same level.

Claims 32-36 (canceled)

37. (previously presented) The package structure in claim 30, wherein said contact conductive layer comprises Ti, Cu, and the combination thereof.

38. (previously presented) The package structure in claim 30, wherein said conductive lines comprise Ni, Cu, Au, and the combination thereof.

39. (previously presented) The package structure in claim 30, wherein a material of said base is glass, silicon, ceramic, or crystal material.

40. (previously presented) The package structure in claim 30, further comprising an epoxy layer formed on a back surface of the base.

41. (original) The package structure in claim 30, wherein said isolation layer comprises epoxy, resin, and the combination thereof.

Claims 42-47 (canceled)

48. (previously presented) The package structure in claim 30, wherein said die is a sawed die and adhered on said base by a picking and placing system.

49. (new) The package structure in claim 30, wherein said first dielectric layer includes silicon rubber, epoxy, resin or BCB to act as a buffer layer to release the stress.

50. (new) The package structure in claim 30, wherein said adhesion material include thermally conductive material.

51. (new) A fan out type package structure, comprising:
a base;
an adhesion material formed on said base;

a die having a plurality of pads on top surface that is opposite to a bottom surface which is on said adhesion material;

a buffer layer formed on said base and adjacent to said die to releases stress, wherein said buffer layer includes silicon rubber, epoxy, resin or BCB;

a dielectric layer formed on said buffer layer and said die, wherein said dielectric layer including a plurality of openings;

a contact conductive layer formed on said plurality of pads of said die and within said openings to electrically couple with said pads, respectively;

a plurality of conductive lines formed on said dielectric layer and in contact with, said contact layer and substantially filling said openings, and said conductive lines being extended out from corresponding said contact conductive layer to corresponding end points, wherein said corresponding end points are located inside a surface of said dielectric layer;

an isolation layer formed on said conductive lines and said dielectric layer; and

solder balls passing through said isolation layer welded on said conductive lines for coupling with said conductive lines, respectively.

52. (new) The package structure in claim 51, wherein said contact layer includes Ti and Cu.

53. (new) The package structure in claim 51, wherein said conductive lines include Cu, Ni and Au.

54. (new) The package structure in claim 51, wherein said adhesion material include thermally conductive material.

55. (new) A fan out type package structure, comprising:

a base;

an adhesion material formed said base;

a die having a plurality of pads on top surface that is opposite to a bottom surface which is on said adhesion material;

a buffer layer formed on said base and adjacent to said die to releases stress, wherein said buffer layer includes silicon rubber, epoxy, resin or BCB;

a dielectric layer formed on said buffer layer and said die, wherein said dielectric layer including a plurality of openings;

a contact conductive layer formed on said plurality of pads of said die and within said openings to electrically couple with said pads, respectively, wherein said contact layer includes Ti and Cu;

a plurality of conductive lines formed on said dielectric layer and in contact with, said contact layer and substantially filling said openings, and said conductive lines being extended out from corresponding said contact conductive layer to corresponding end points, wherein said corresponding end points are located inside a surface of said dielectric layer, wherein said conductive lines include Cu, Ni and Au;

an isolation layer formed on said conductive lines and said dielectric layer; and

solder balls passing through said isolation layer welded on said conductive lines for coupling with said conductive lines, respectively.

56. (new) The package structure in claim 55, wherein said adhesion material include thermally conductive material.